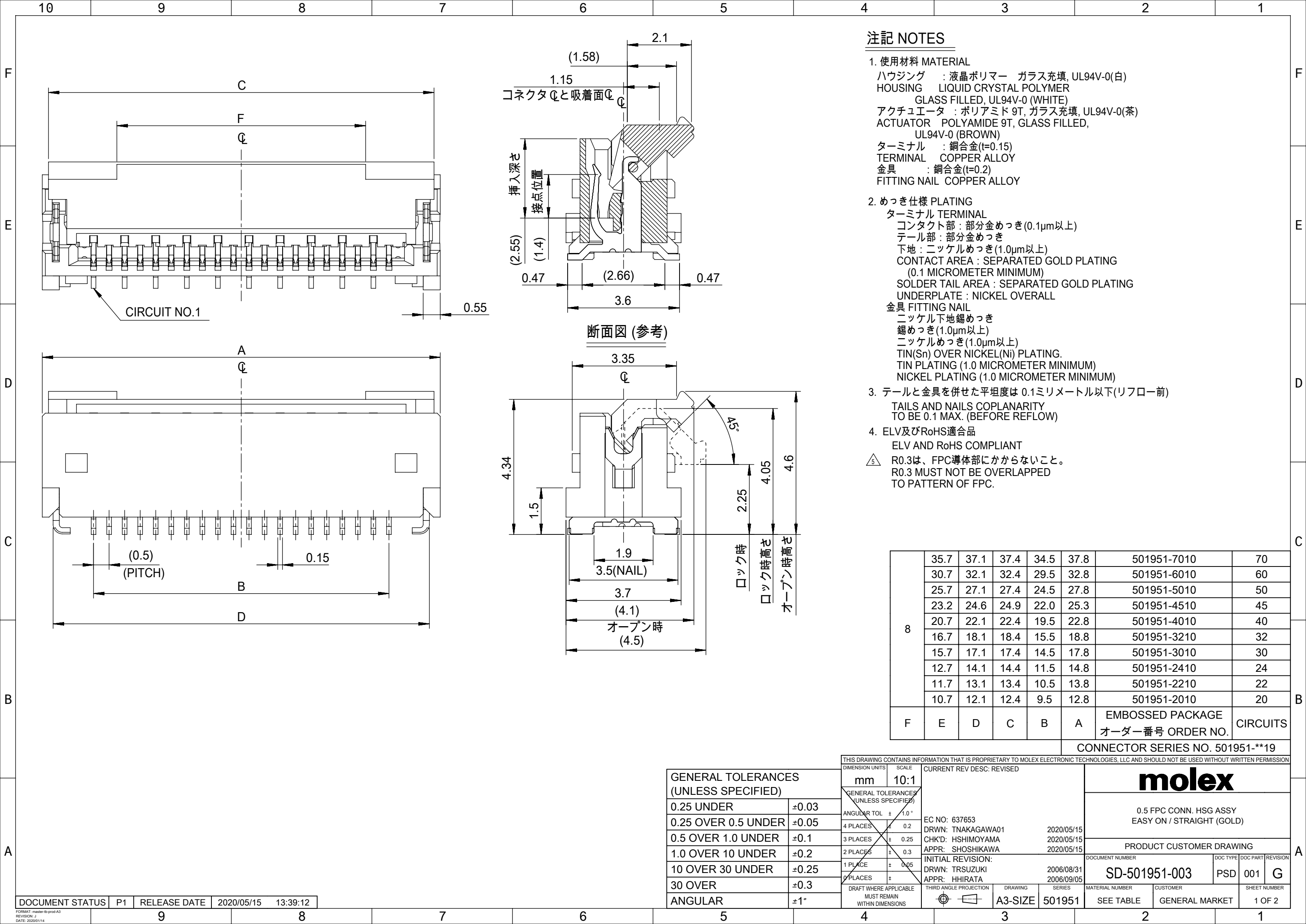




注記 NOTES

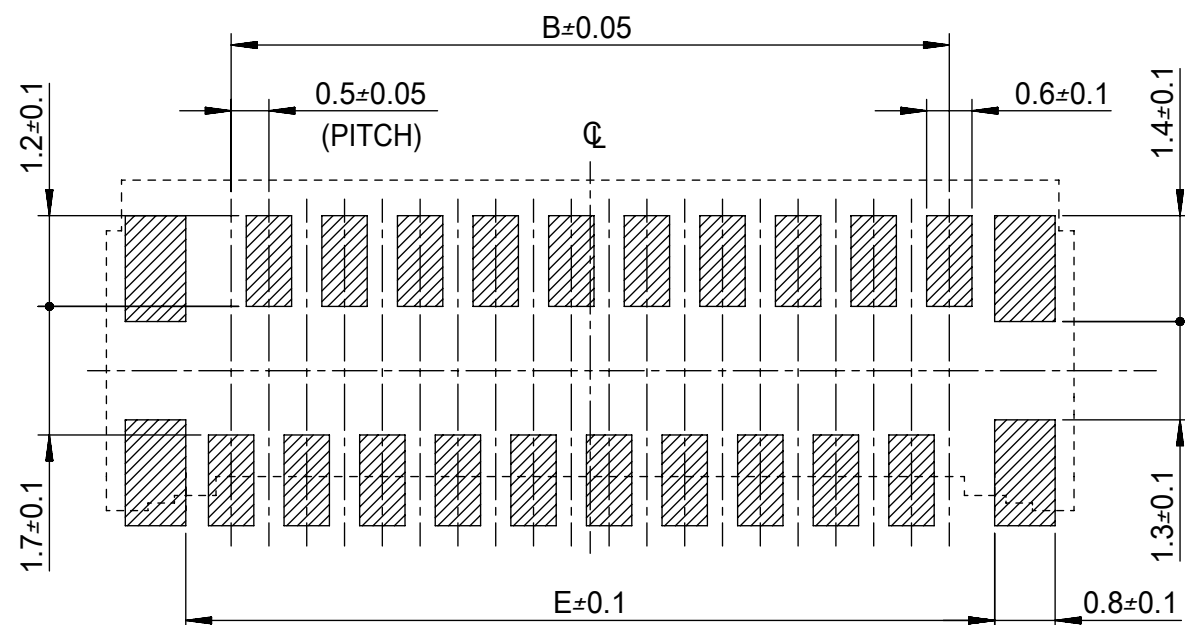
1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填, UL94V-0(白)
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0 (WHITE)
アクチュエータ : ポリアミド 9T, ガラス充填, UL94V-0(茶)
ACTUATOR POLYAMIDE 9T, GLASS FILLED, UL94V-0 (BROWN)
ターミナル : 銅合金(t=0.15)
TERMINAL COPPER ALLOY
金具 : 銅合金(t=0.2)
FITTING NAIL COPPER ALLOY
2. めっき仕様 PLATING
ターミナル TERMINAL
コンタクト部 : 部分金めっき (0.1μm以上)
テール部 : 部分金めっき
下地 : ニッケルめっき (1.0μm以上)
CONTACT AREA : SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA : SEPARATED GOLD PLATING
UNDERPLATE : NICKEL OVERALL
金具 FITTING NAIL
ニッケル下地 錫めっき
錫めっき (1.0μm以上)
ニッケルめっき (1.0μm以上)
TIN(Sn) OVER NICKEL(Ni) PLATING.
TIN PLATING (1.0 MICROMETER MINIMUM)
NICKEL PLATING (1.0 MICROMETER MINIMUM)
3. テールと金具を併せた平坦度は 0.1ミリメートル以下(リフロー前)
TAILS AND NAILS COPLANARITY TO BE 0.1 MAX. (BEFORE REFLOW)
4. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- △ R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

8	35.7	37.1	37.4	34.5	37.8	501951-7010	70
	30.7	32.1	32.4	29.5	32.8	501951-6010	60
	25.7	27.1	27.4	24.5	27.8	501951-5010	50
	23.2	24.6	24.9	22.0	25.3	501951-4510	45
	20.7	22.1	22.4	19.5	22.8	501951-4010	40
	16.7	18.1	18.4	15.5	18.8	501951-3210	32
	15.7	17.1	17.4	14.5	17.8	501951-3010	30
	12.7	14.1	14.4	11.5	14.8	501951-2410	24
	11.7	13.1	13.4	10.5	13.8	501951-2210	22
	10.7	12.1	12.4	9.5	12.8	501951-2010	20
F	E	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES NO. 501951-**19

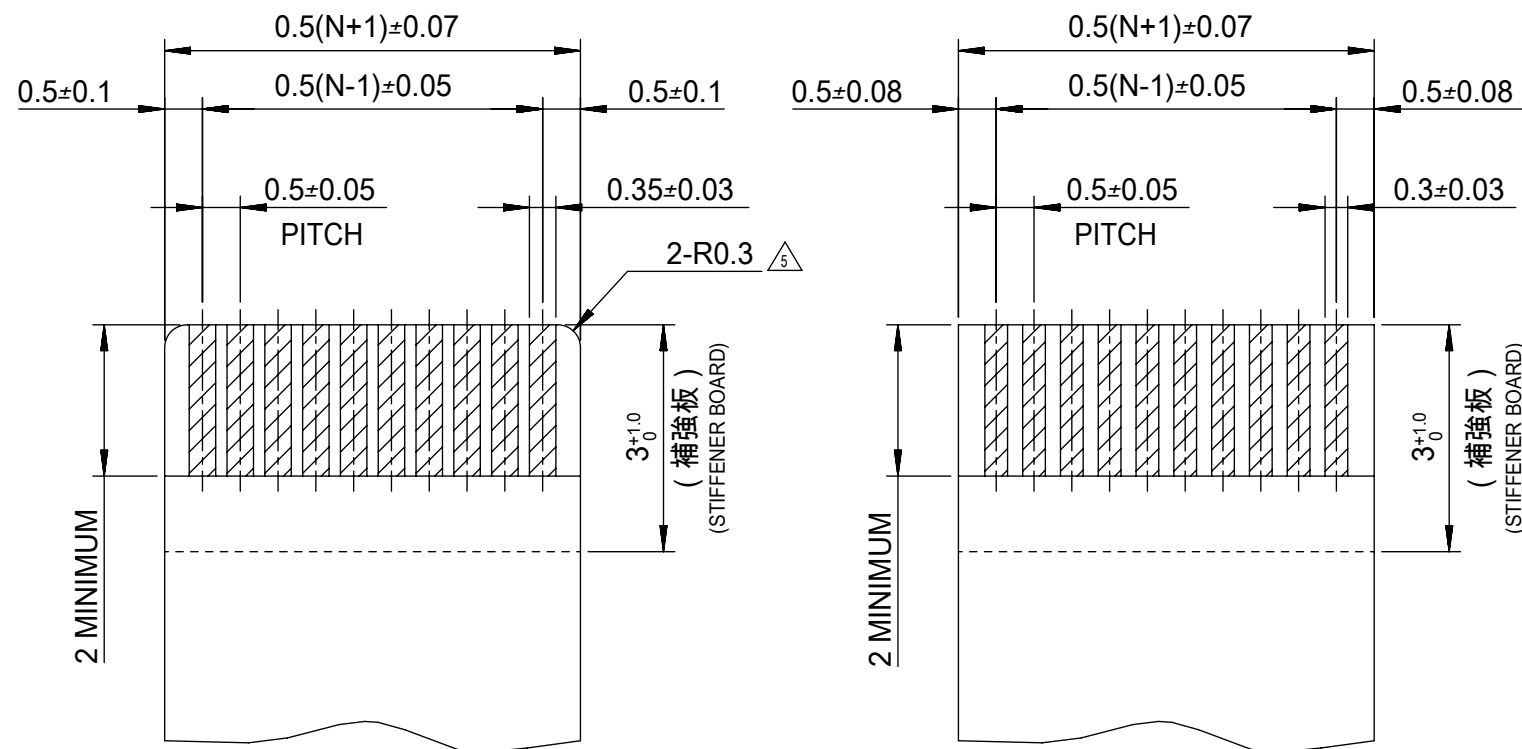
GENERAL TOLERANCES (UNLESS SPECIFIED)		mm		10:1		CURRENT REV DESC: REVISED		molex				
0.25 UNDER	±0.03	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0 ° 4 PLACES ± 0.2 3 PLACES ± 0.25 2 PLACES ± 0.3 1 PLACE ± 0.05 0 PLACES ± DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		EC NO: 637653 DRWN: TNAKAGAWA01 CHK'D: HSHIMOYAMA APPR: SHOSHIKAWA INITIAL REVISION: DRWN: TRSUZUKI APPR: HHIRATA		2020/05/15 2020/05/15 2020/05/15 2006/08/31 2006/09/05		0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)				
0.25 OVER 0.5 UNDER	±0.05							PRODUCT CUSTOMER DRAWING				
0.5 OVER 1.0 UNDER	±0.1							DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
1.0 OVER 10 UNDER	±0.2							SD-501951-003		PSD	001	G
10 OVER 30 UNDER	±0.25							MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
30 OVER	±0.3							SEE TABLE		GENERAL MARKET		1 OF 2
ANGULAR	±1°	THIRD ANGLE PROJECTION		DRAWING	SERIES							
				A3-SIZE	501951							

DOCUMENT STATUS	P1	RELEASE DATE	2020/05/15	13:39:12
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参考基板レイアウト (マウント面)

P.C.BOARD PATTERN DIMENSION(REF.)
(MOUNT AREA)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ : 0.3 ± 0.05)
(THICKNESS : 0.3 ± 0.05)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

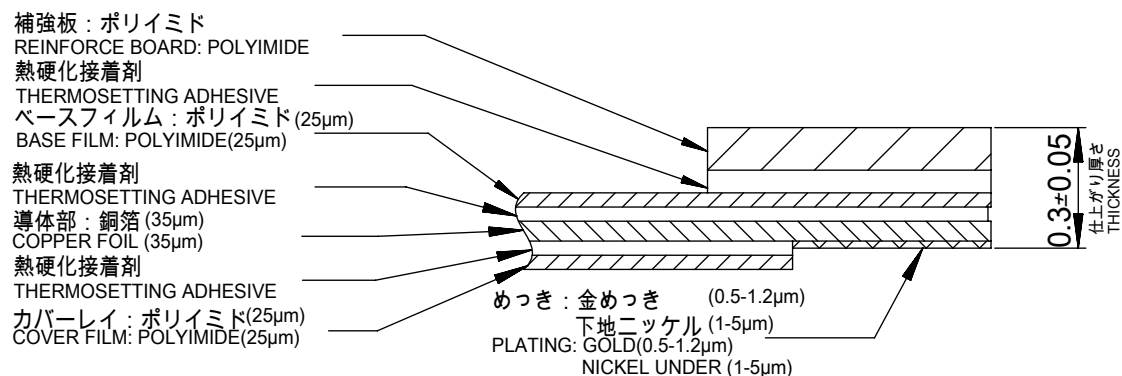
(仕上がり厚さ : 0.3 ± 0.05)
(THICKNESS : 0.3 ± 0.05)

N : 極数
N: CIRCUITS

FPCについて ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

RECOMMENDED MATERIAL/THICKNESS.
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.



FPC構成推奨仕様

STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC

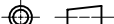
打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟箔銅35μmまたは50μmを推奨します。
FFCに規定された定格温度がFFC単体前提である場合が御座います。
コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避するため、実機での評価/確認をお願い致します。

RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE

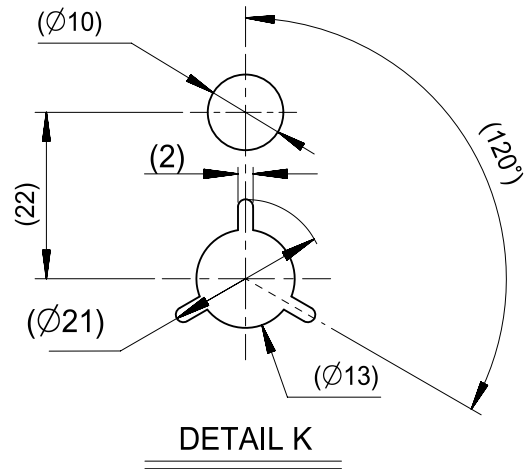
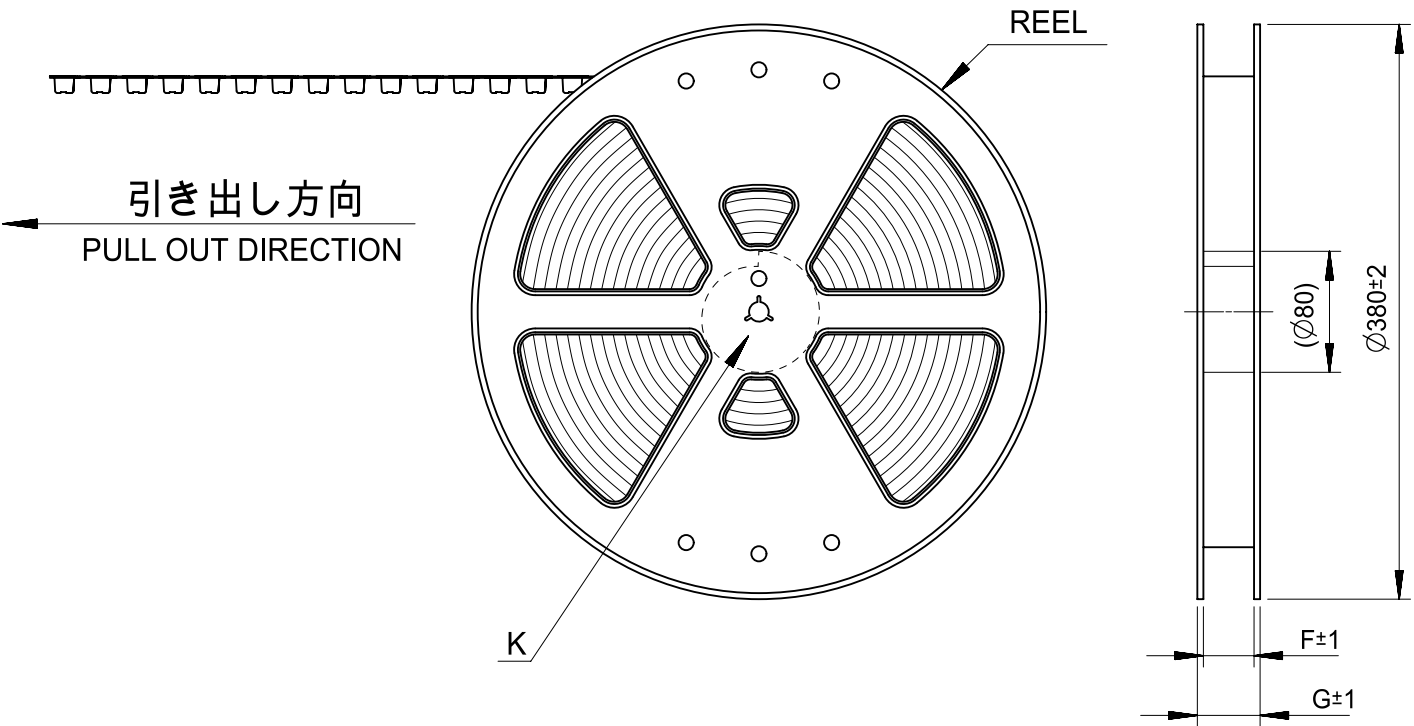
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL

RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC,)

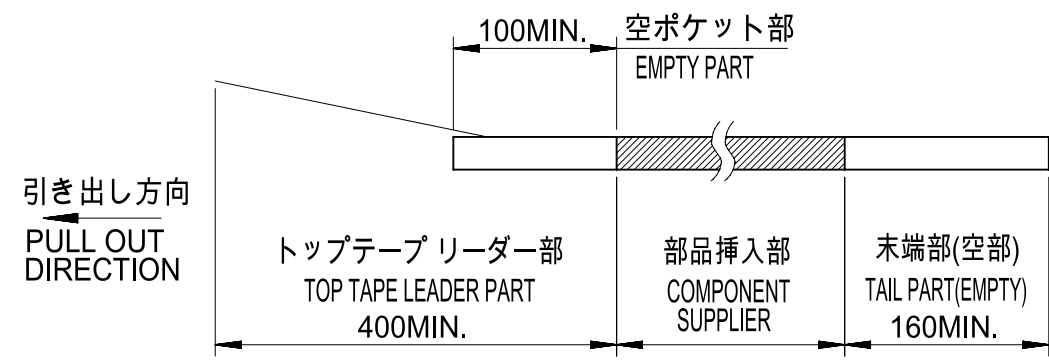
GENERAL TOLERANCES (UNLESS SPECIFIED)		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		DIMENSION UNITS mm	SCALE 10:1
0.25 UNDER	±0.03	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0° 4 PLACES ± 0.2 3 PLACES ± 0.25 2 PLACES ± 0.3 1 PLACE ± 0.05 0 PLACES ± CURRENT REV DESC: REVISED EC NO: 637653 DRWN: TNAKAGAWA01 2020/05/15 CHK'D: HSHIMOYAMA 2020/05/15 APPR: SHOSHIKAWA 2020/05/15 INITIAL REVISION: DRWN: TRSUZUKI 2006/08/31 APPR: HHIRATA 2006/09/05 DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
0.25 OVER 0.5 UNDER	±0.05		
0.5 OVER 1.0 UNDER	±0.1		
1.0 OVER 10 UNDER	±0.2		
10 OVER 30 UNDER	±0.25		
30 OVER	±0.3		
ANGULAR	±1°	THIRD ANGLE PROJECTION  DRAWING A3-SIZE SERIES 501951	

molex			
0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)			
PRODUCT CUSTOMER DRAWING			
DOCUMENT NUMBER		DOC TYPE	DOC PART
SD-501951-003		PSD	001
MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
SEE SHEET 1		GENERAL MARKET	2 OF 2

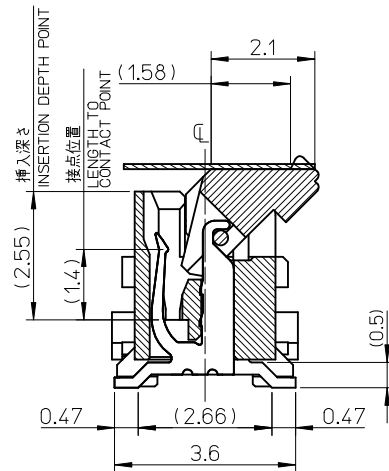
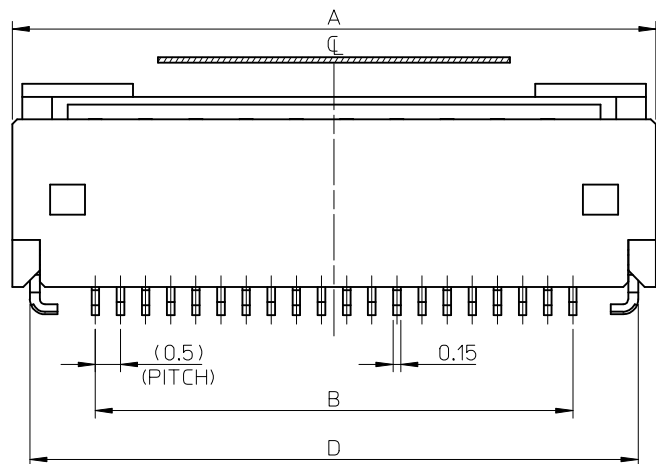
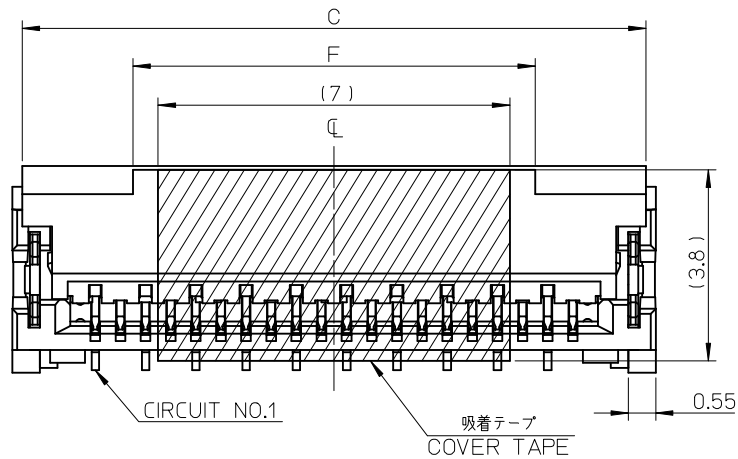


NOTES

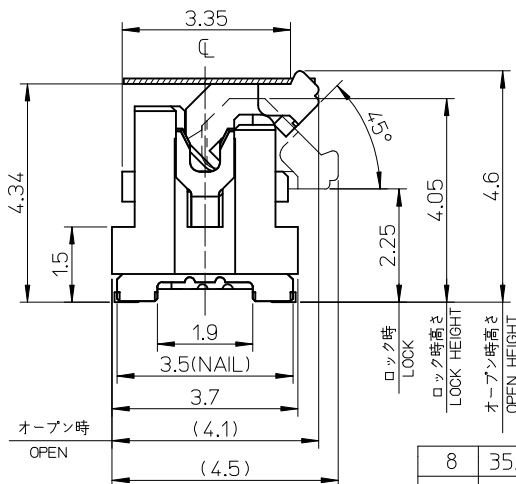
- 製品詳細寸法については図面 SD-501951-003を参照下さい。
FOR DIMENSIONS OF PRODUCT, REFER TO SD-501951-003.
- 梱包数量：2000個/リール
NUMBER OF CONNECTORS：2000PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
- 5.材料 MATERIAL
キャリアテープ：ポリスチレン
CARRIER TAPE：POLYSTYRENE
トップテープ：ポリエチレンテレフタレート、ポリエチレン
TOP TAPE：POLYETHYLENE TEREPHTHALATE , POLYETHYLENE
リール：ポリスチレン<リサイクル材を含む>
REEL：POLYSTYRENE<RECYCLE MATERIAL CONTAINED>
- 6.ELV及びRoHS適合品 ELV AND RoHS COMPLIANT



断面図 (参考)
SECTION (REFERENCE)



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液屋ポリマー ガラス充填, UL94V-0(白)
HOUSING : LIQUID CRYSTAL POLYMER
GLASS FILLED, UL94V-0 (WHITE)
アクチュエータ : ポリアミド, ガラス充填, UL94V-0(茶)
ACTUATOR : POLYAMIDE, GLASS FILLED,
UL94V-0 (BROWN)
ターミナル : 銅合金(t=0.15)
TERMINAL : COPPER ALLOY
金具 : 銅合金(t=0.2)
FITTING NAIL : COPPER ALLOY
吸着テープ : ポリアミド(t=0.125)
COVER TAPE : POLYIMIDE(t=0.125)

2. めっき仕様 PLATING

ターミナル TERMINAL

コンタクト部: 部分金めっき 0.1マイクロメートル以上
CONTACT AREA :SEPARATED GOLD PLATING 0.1μm MIN.
テール部: 部分金めっき
TAIL AREA :SEPARATED GOLD PLATING
下地: ニッケルめっき 1マイクロメートル以上
UNDERPLATE: NICKEL OVERALL 1.0μm MIN.

金具 FITTING NAIL

銅めっき 1.0マイクロメートル以上
TIN PLATING 1.0μm MIN.
下地: ニッケルめっき 1マイクロメートル以上
UNDERPLATE: NICKEL OVERALL 1.0μm MIN.

3. テールと金具を併せた平坦度は 0.1ミリメートル以下
TAILS AND NAILS COPLANARITY
TO BE 0.1 MAX.

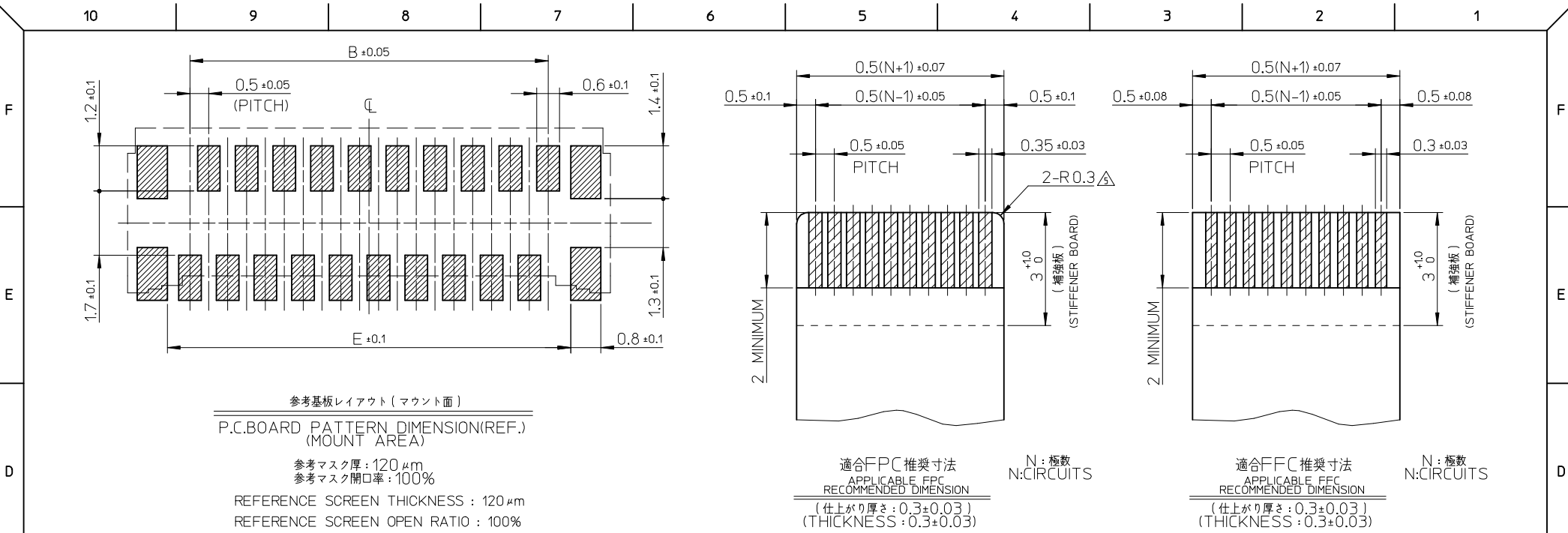
4. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

△ R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED
TO PATTERN OF FPC.

6. 本製品は 501951-7019 の吸着テープ付き品である。
THIS PRODUCT IS COVER TAPE VERSION OF 501951-7019.

8	35.7	37.1	37.4	34.5	37.8	501951-7020	501951-7029	70
F	E	D	C	B	A	EMBOSSED TAPE	製品番号	極数
						ORDER NO. オーダー番号	MATERIAL NO.	CIRCUITS
						MODEL NO. 501951-**-29		

RELEASED EC NO: J2016-0731 DRAWN:KONDO CHKD:K TAKAHASHI APPR:KMORI KAWA	2016/01/14 2016/01/14 2016/01/14 2016/01/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION			
			0.25 UNDER		±0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)					
			0.25 OVER 0.5 UNDER		±0.2	NKONDO 2016/01/14							
			0.5 OVER 1.0 UNDER		±0.2	CHECKED BY DATE							
			1.0 OVER 10 UNDER		±0.2	KTAKAHASHI 2016/01/14							
			10 OVER 30 UNDER		±0.25	APPROVED BY DATE							
			30 OVER		±0.3	KMORI KAWA 2016/01/15							
			ANGULAR ±1 °			MATERIAL NO.			DOCUMENT NO. SD-501951-009			SHEET NO. 1 OF 2	
						SEE CHART							
			0	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

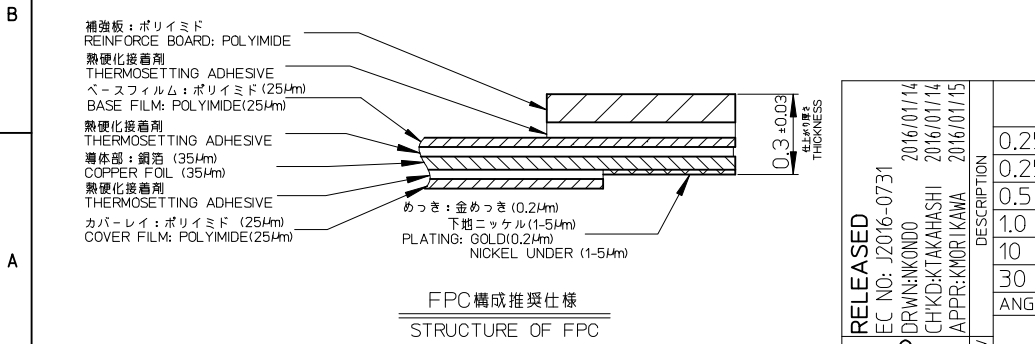


FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

ABOUT FPC

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.



FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。
FFCに規定された定格温度がFFC単体前提である場合がございます。
コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避する為、実機での評価/確認をお願い致します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

RELEASED		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
EC No. J2016-0731	DRWN: NKONDO 2016/01/14	0.25 UNDER	± 0.2	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)		molex	
0	CHKD: TAKAHASHI 2016/01/14	0.25 OVER 0.5 UNDER	± 0.2	CHECKED BY	DATE				
	APPR: KMORIKAWA 2016/01/15	0.5 OVER 1.0 UNDER	± 0.2	APPROVED BY	DATE	---		SD-501951-009	
		1.0 OVER 10 UNDER	± 0.2	MATERIAL NO.	2016/01/15	DOCUMENT NO.		SHEET NO. 2 OF 2	
		10 OVER 30 UNDER	± 0.25	SEE SHEET 1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		30 OVER	± 0.3						
		ANGULAR ±1 °							
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							